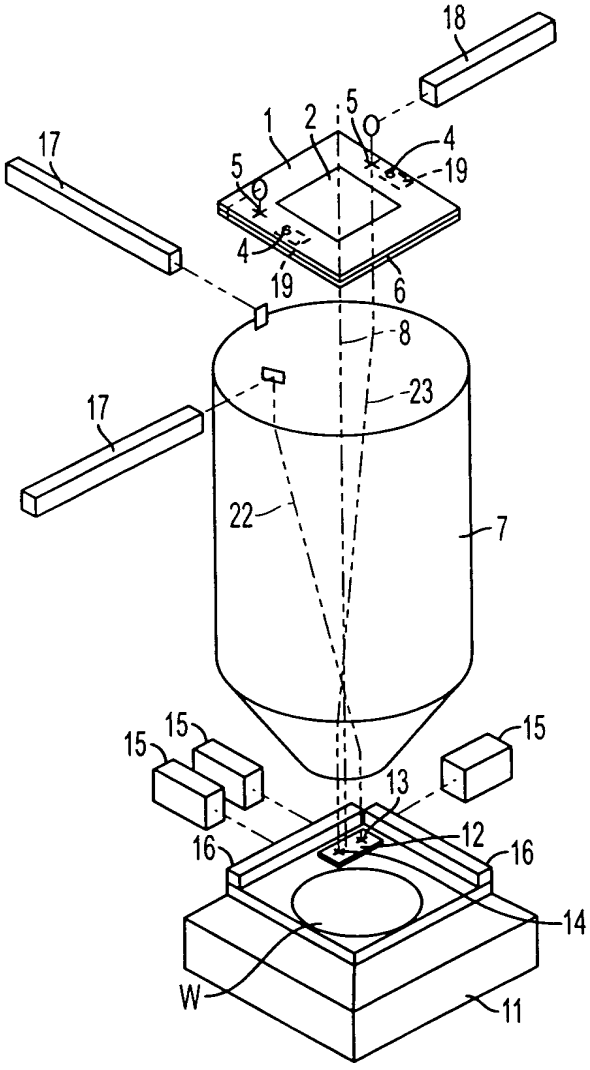


FIG. 1A
(PRIOR ART)

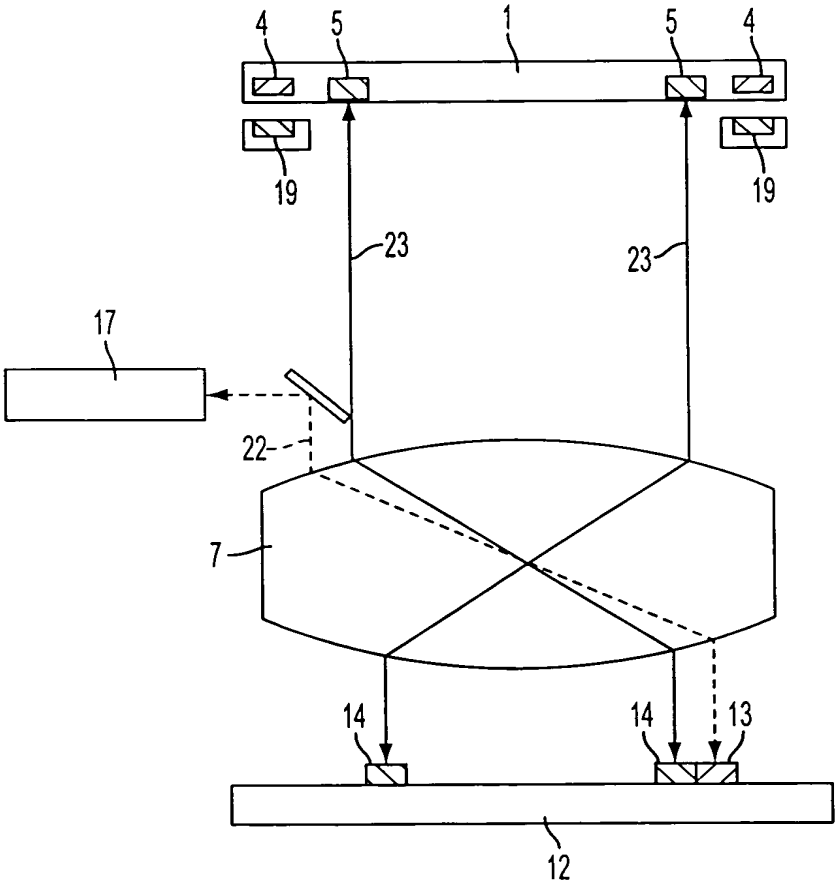


FIG. 1B
(PRIOR ART)

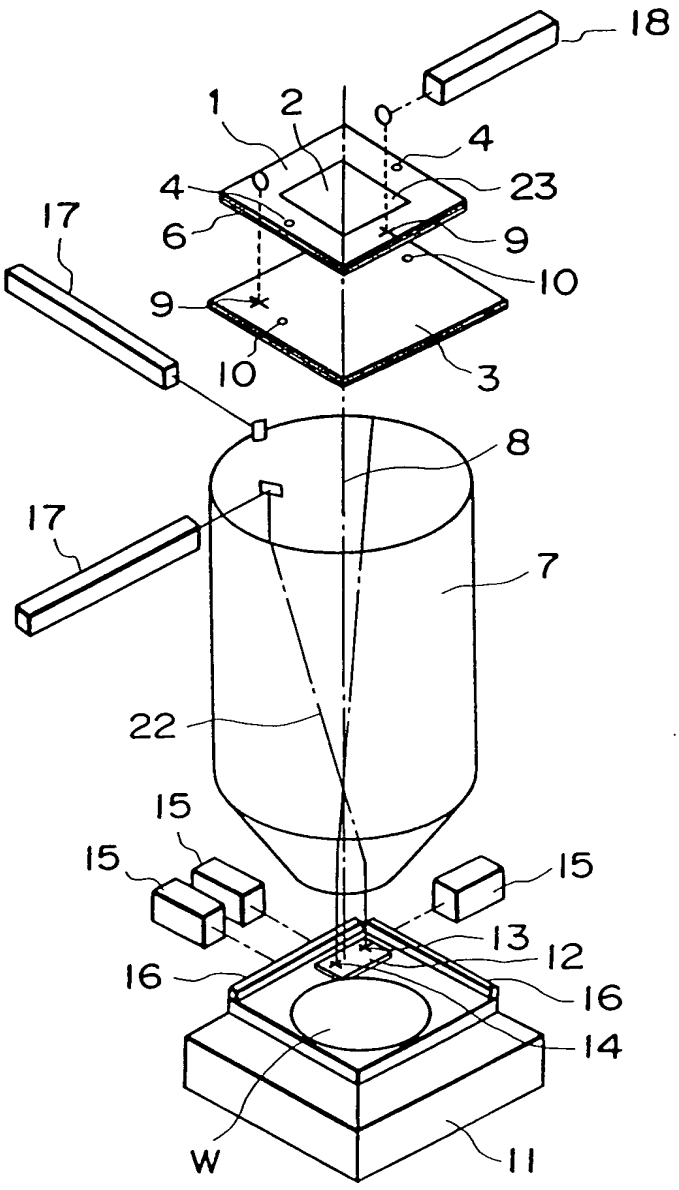


FIG. 2A

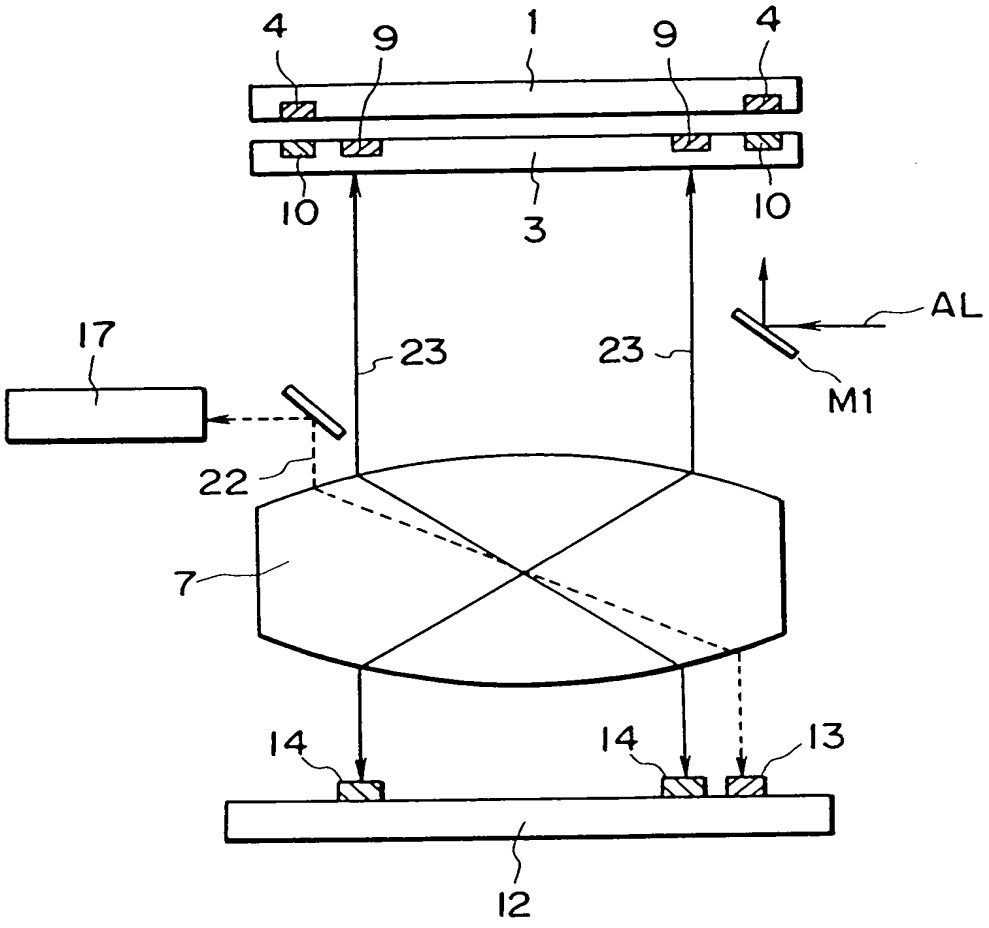


FIG. 2B

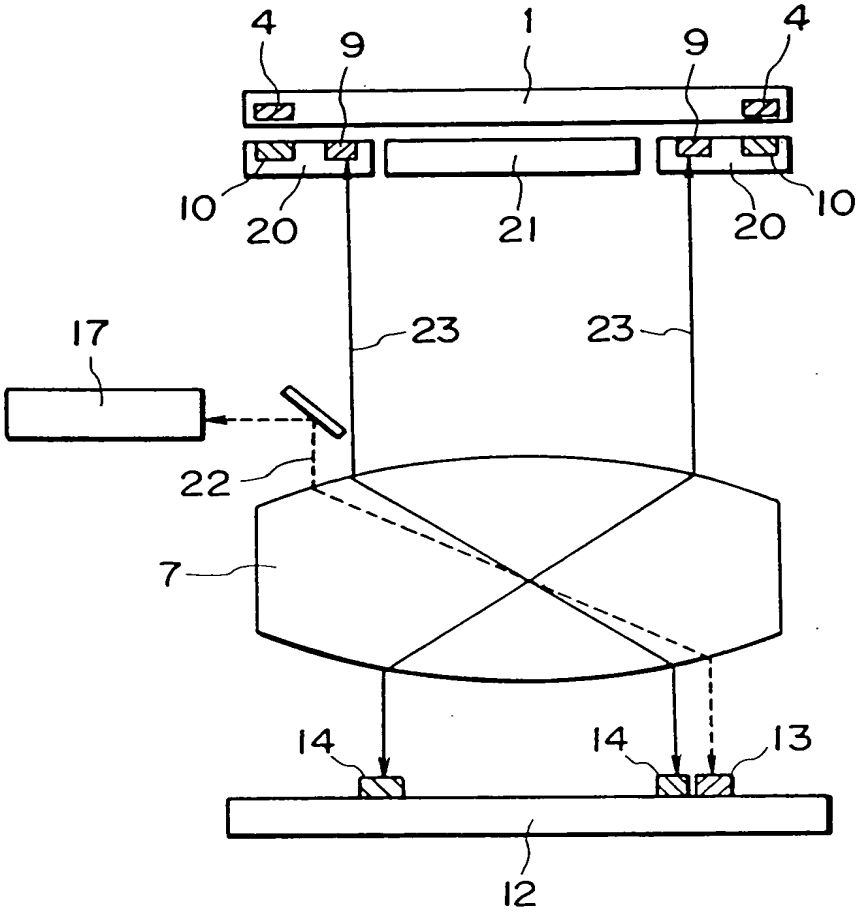


FIG. 3

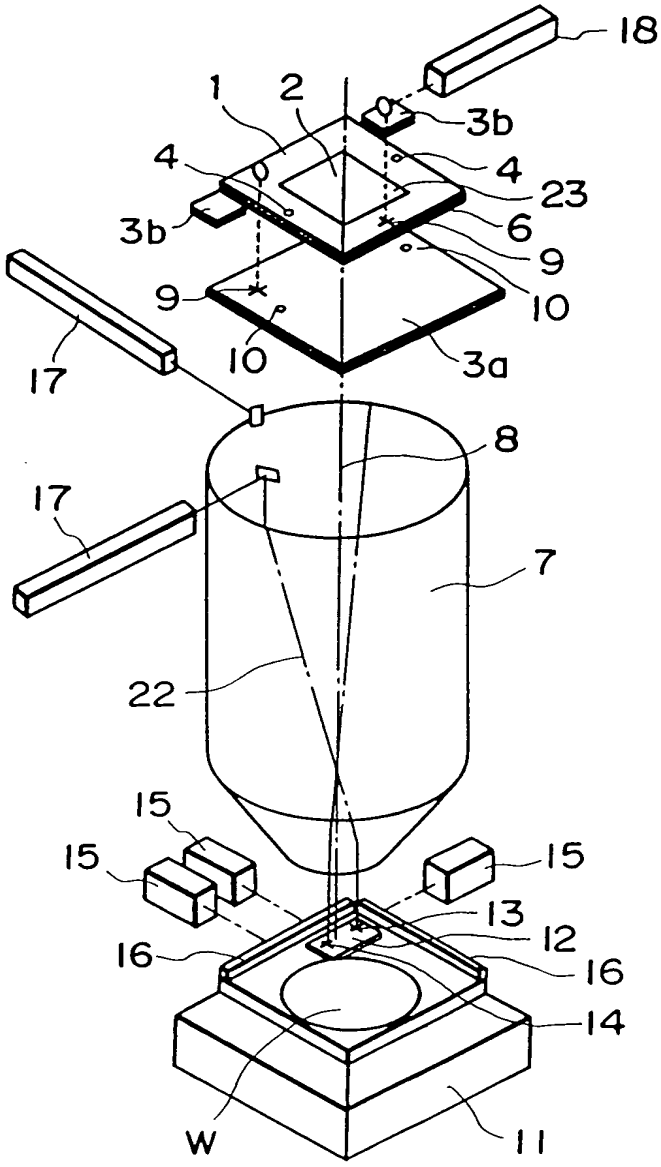


FIG. 4

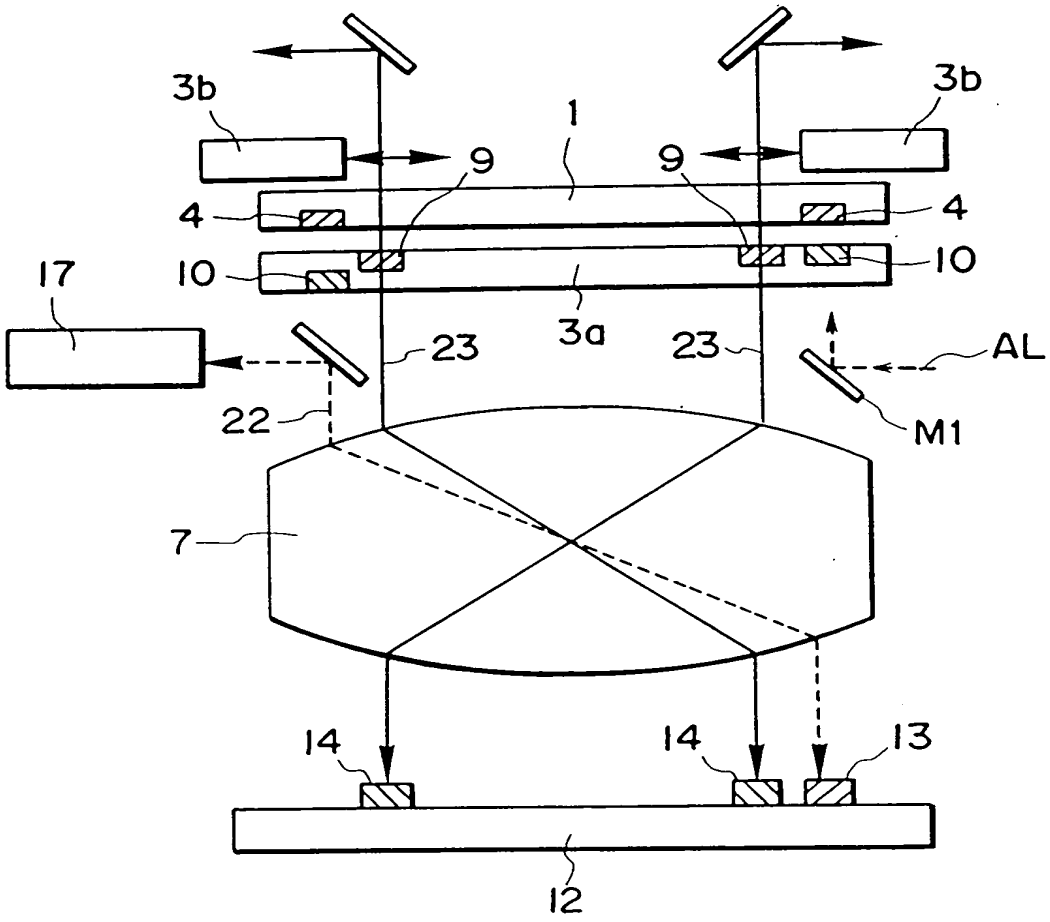


FIG. 5

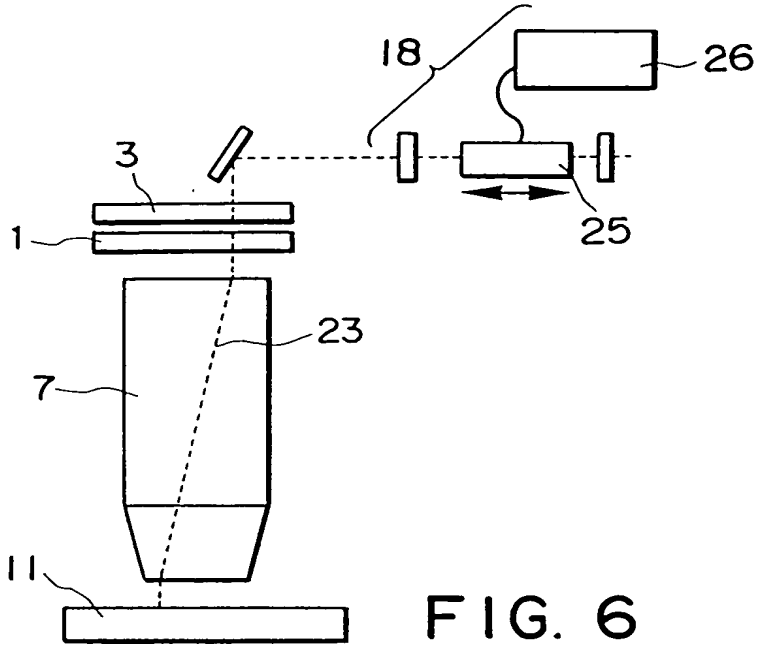
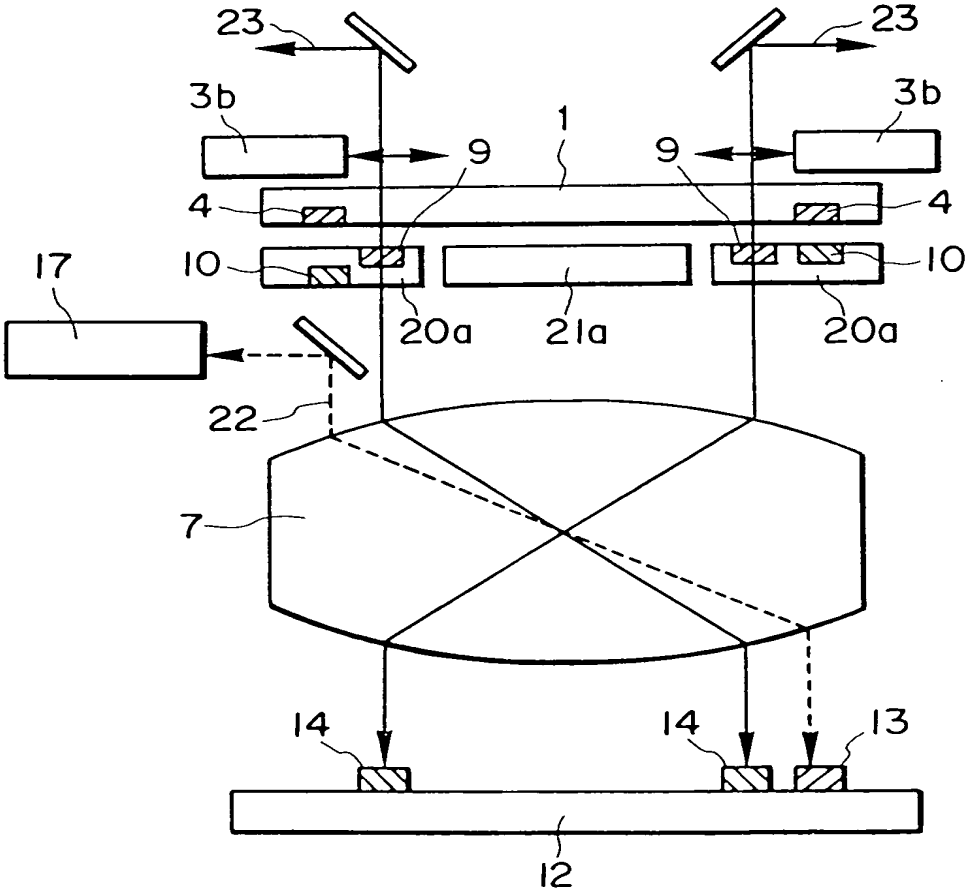

18
26
3
25
1
23
7
11

FIG. 6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3b
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20a
21a
20a
22
7
14
14
13
12

FIG. 7

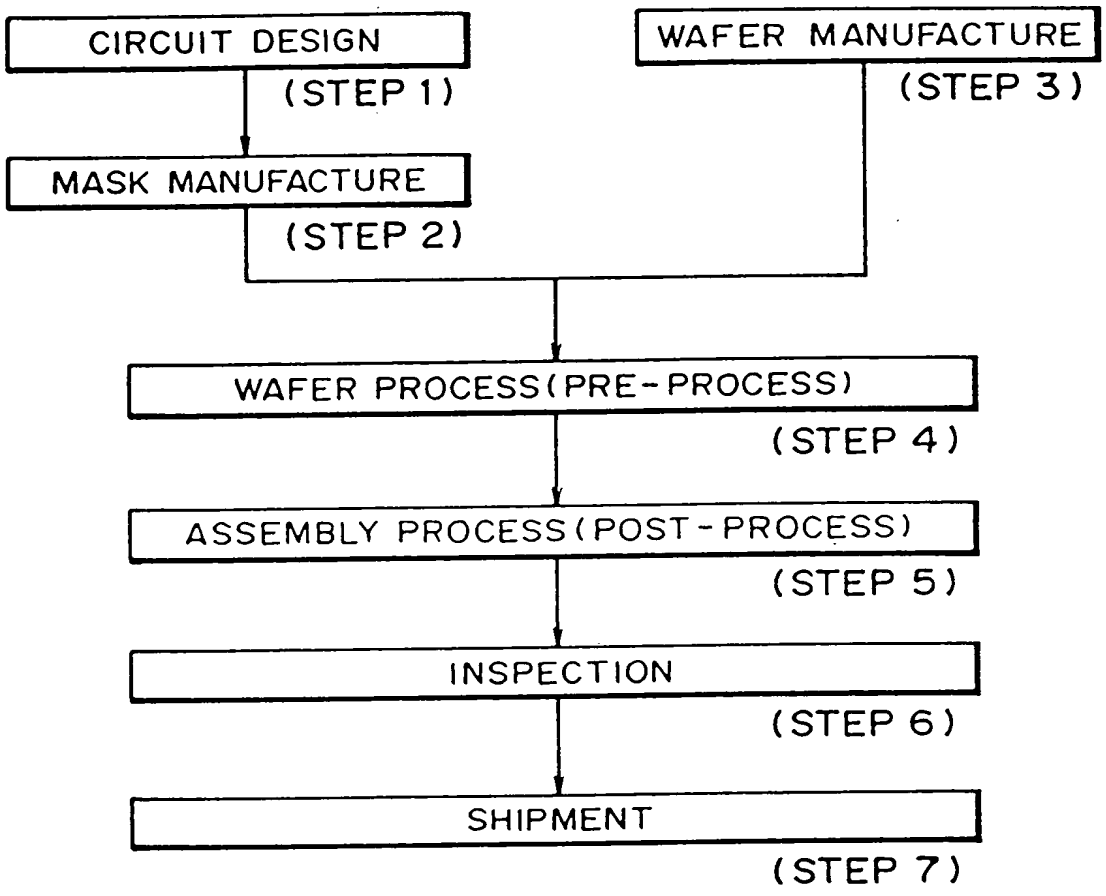
CIRCUIT DESIGN
(STEP 1)
MASK MANUFACTURE
(STEP 2)
WAFER MANUFACTURE
(STEP 3)
WAFER PROCESS(PRE-PROCESS)
(STEP 4)
ASSEMBLY PROCESS(POST-PROCESS)
(STEP 5)
INSPECTION
(STEP 6)
SHIPMENT
(STEP 7)

FIG. 8

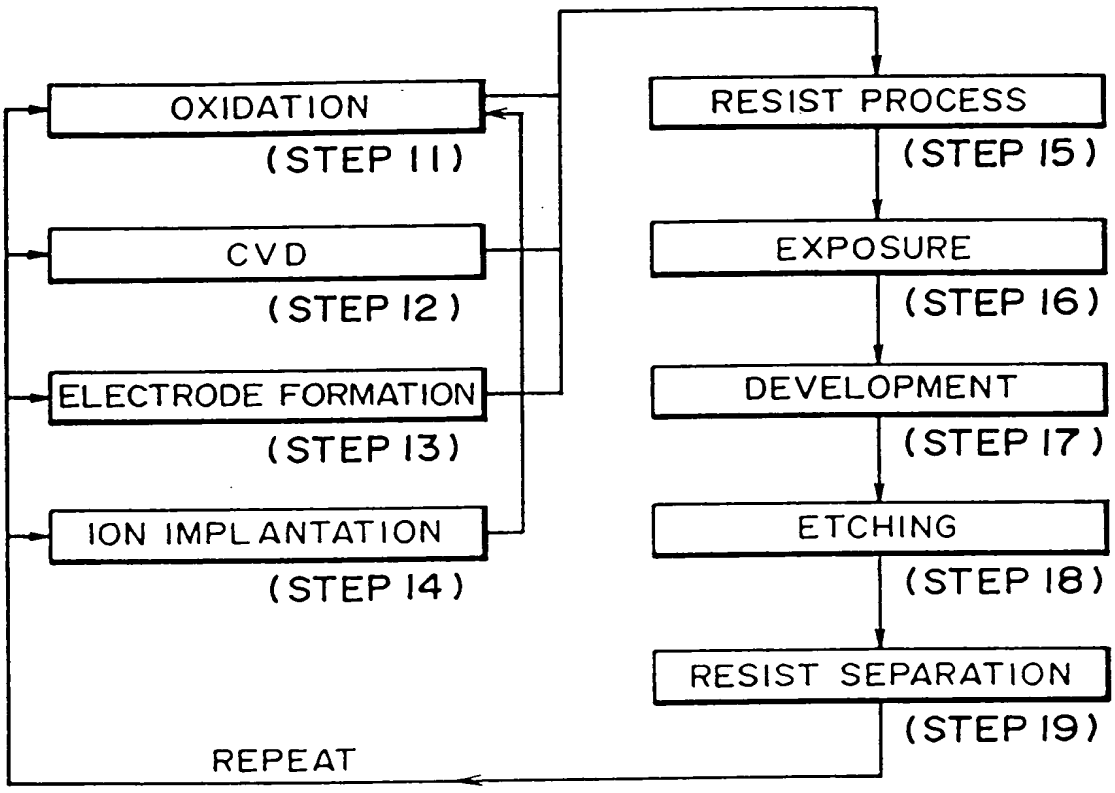
OXIDATION
(STEP 11)
CVD
(STEP 12)
ELECTRODE FORMATION
(STEP 13)
ION IMPLANTATION
(STEP 14)
RESIST PROCESS
(STEP 15)
EXPOSURE
(STEP 16)
DEVELOPMENT
(STEP 17)
ETCHING
(STEP 18)
RESIST SEPARATION
(STEP 19)
REPEAT

FIG. 9